Product / Package Information

Package	LFCSP - Stacked Die
Body Size (mm)	6 X 6 X 0.95 (3.8 EP)
LeadCount	32
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.15E-02	86.91	869100	44.20	441973
Thermosets	Epoxy & Phenol Resin	Proprietary	6.10E-03	12.78	127800	6.50	64992
Other inorganic materials	Carbon black	1333-86-4	1.48E-04	0.31	3100	0.16	1576
Subtotal			4.77 E-02	100.00	1000000	50.85	508541

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.61 E-02	96.20	962000	38.45	384546
Copper & its alloys	Nickel	7440-02-0	1.13 E-03	3.00	30000	1.20	11992
Copper & its alloys	Silicon	7440-21-3	2.44 E-04	0.65	6500	0.26	2598
Copper & its alloys	Magnesium	7439-95-4	5.63 E-05	0.15	1500	0.06	600
Subtotal			3.75 E-02	100.00	1000000	39.97	399736

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.40 E-04	100.0	1000000	0.68	6820

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.70 E-03	100.0	1000000	1.81	18117

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.26 E-03	99.00	990000	1.34	13399
Precious metals	Palladium	7440-05-3	1.27 E-05	1.00	10000	0.01	135
Subtotal			1.27 E-03	100.0	1000000	1.35	13534

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	4.19 E-03	100.0	1000000	4.47	44652

Die Attach 1

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.42 E-04	73.40	734000	0.58	5773
Thermoset	Epoxy Resin	Proprietary	1.35 E-04	18.35	183500	0.14	1443
Other inorganic materials	Metal oxide	Proprietary	2.03 E-05	2.75	27500	0.02	216
Others	Curing and hardening agent	Proprietary	2.03 E-05	2.75	27500	0.02	216
Other organic materials	Gamma Butyrolactone	96-48-0	2.03 E-05	2.75	27500	0.02	216
Subtotal			7.38 E-04	100.0	1000000	0.79	7865

Die Attach 2

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Thermoset	Resin	Proprietary	4.00 E-05	58.0	580000	0.04	426
Other organic materials	Polytetrafluoroethylene	9002-84-0	2.90 E-05	42.0	420000	0.03	309
Subtotal			6.90 E-05	100.0	1000000	0.07	735

	Weight (g)			Percentage (%)	PPM
Package Totals	**9.38 E-02**			**100**	**1000000**

ANALOG DEVICES